

SOT1332-1

plastic low profile fine-pitch ball grid array package; 267 balls
8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA267
Package type industry code	LFBGA267
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	20-9-2012

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		16.9	-	17	17.1	mm
E	package width		16.9	-	17	17.1	mm
A	seated height		1.25	-	1.35	1.5	mm
e	nominal pitch		-	-	0.8	-	mm
n ₂	actual quantity of termination		-	-	267	-	



2. Package outline

LFBGA267: plastic low profile fine-pitch ball grid array package; 267 balls

SOT1332-1

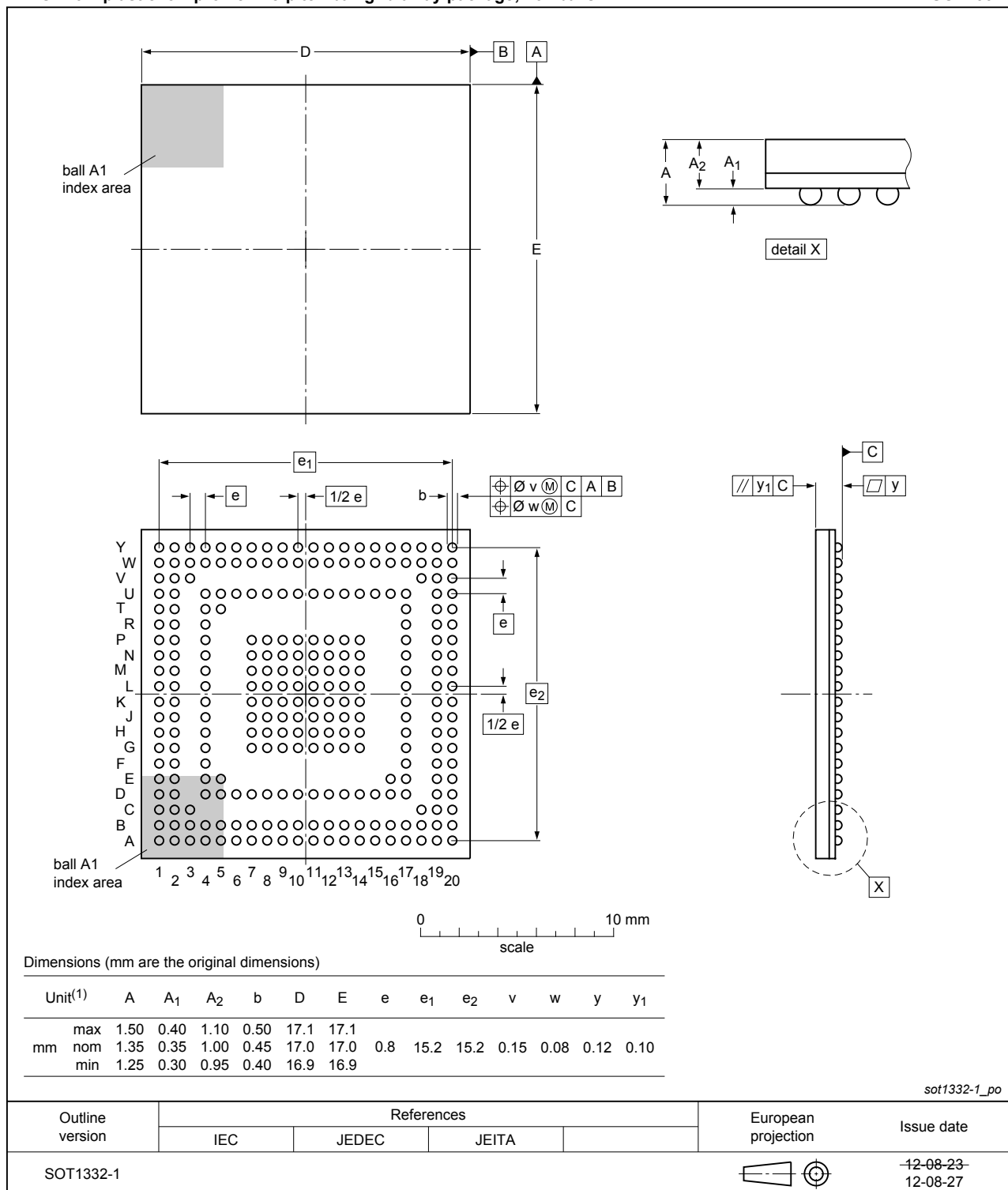
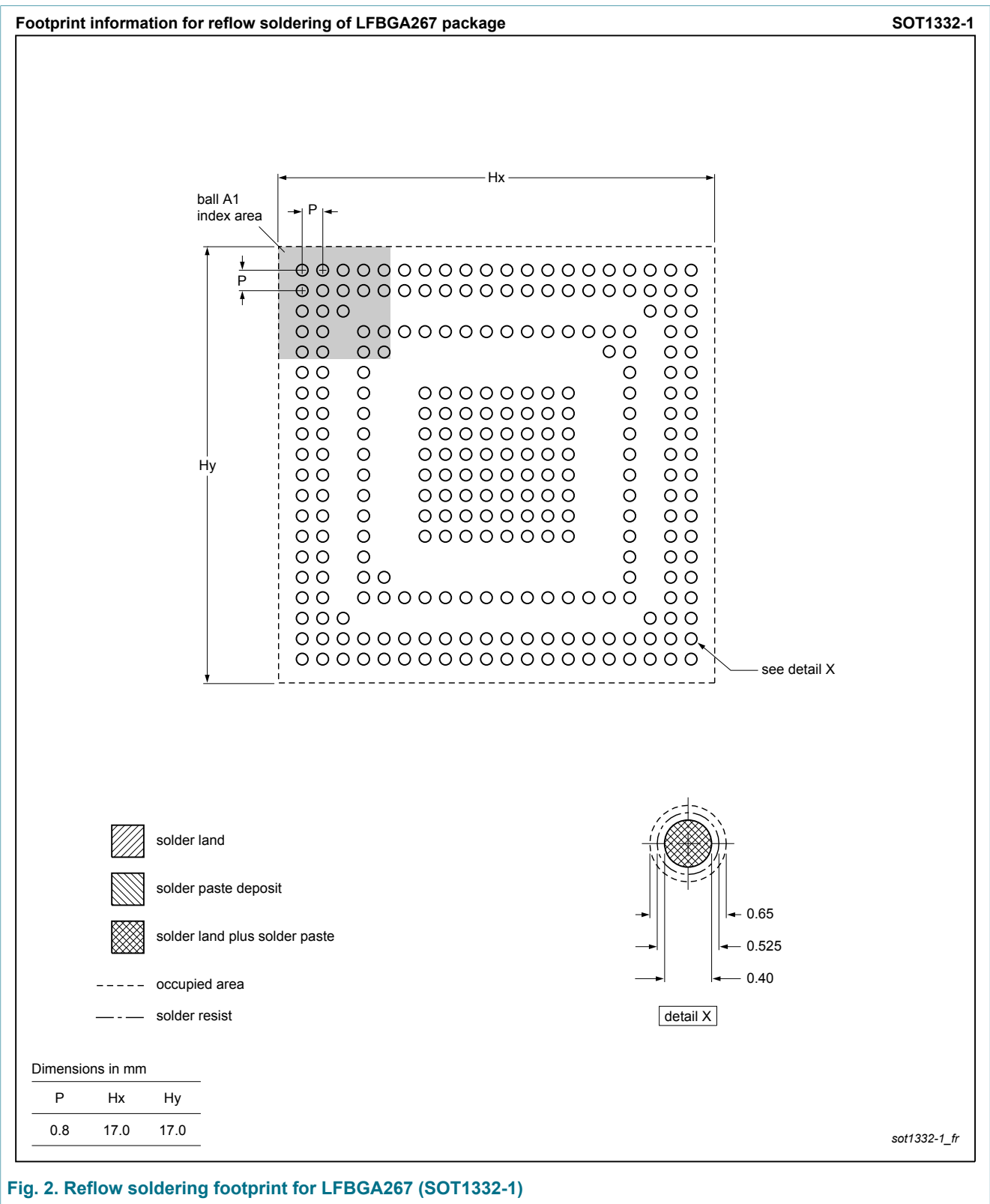


Fig. 1. Package outline LFBGA267 (SOT1332-1)

3. Soldering



4. Legal information

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